ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				Thi lev	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and M	fg Informat	ion		
Supplier Inform															
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
onsemi											2025-05-12				
Contact Name		-	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	rds	]	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Represe	ntative*	-	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards Pro				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date Version		Manufacturing Site		Weight*	UOM	Unit Type		
		NCV8130BMX120TC 300mA VLDO option, Vout=1		300mA VLDO Bi option, Vout=1.2V	ias Rail CMOS Vre	eg, HZ	2025-05-12 MY1		MY1	:	1.87	mg	Each		
Ianufacturing l	Proccess Information	1													
Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSL F		ating	Peak Process Body Temperature Max Time at Pea		Temperat	ure Numl	per of Reflow Cyc	eles				
Matte Tin (Sn) - annealed		CU	CU Alloy 1		1		260	C 30		secon	ds 3				
omments															
vel 1 - maximum ti	ime at peak temperature d	luring solde	ering is 10-30	0 seconds											
or more informatio	on regarding material com	position pl	lease refer to	page 3				·							

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correction this form. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg
Die Attach	0.03	mg	Supplier	Silver (Ag)	7440-22-4		0.0225	mg
			Supplier	Epoxy resins	129915-35-1		0.0075	mg
Lead Frame	0.82	mg	Supplier	Silver (Ag)	7440-22-4		0.0328	mg
			Supplier	Tin (Sn)	7440-31-5		0.0021	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0018	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0021	mg
			Supplier	Copper (Cu)	7440-50-8		0.7813	mg
Mold Compound-Black	0.88	mg		Epoxy resin	proprietary data		0.0616	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0616	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.132	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0044	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.6204	mg
Plating	0.02	mg	Supplier	Tin (Sn)	7440-31-5		0.02	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg